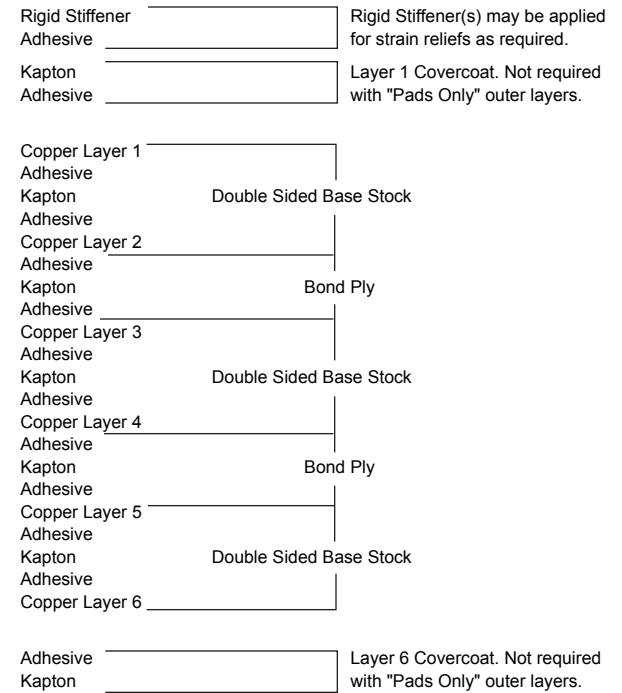
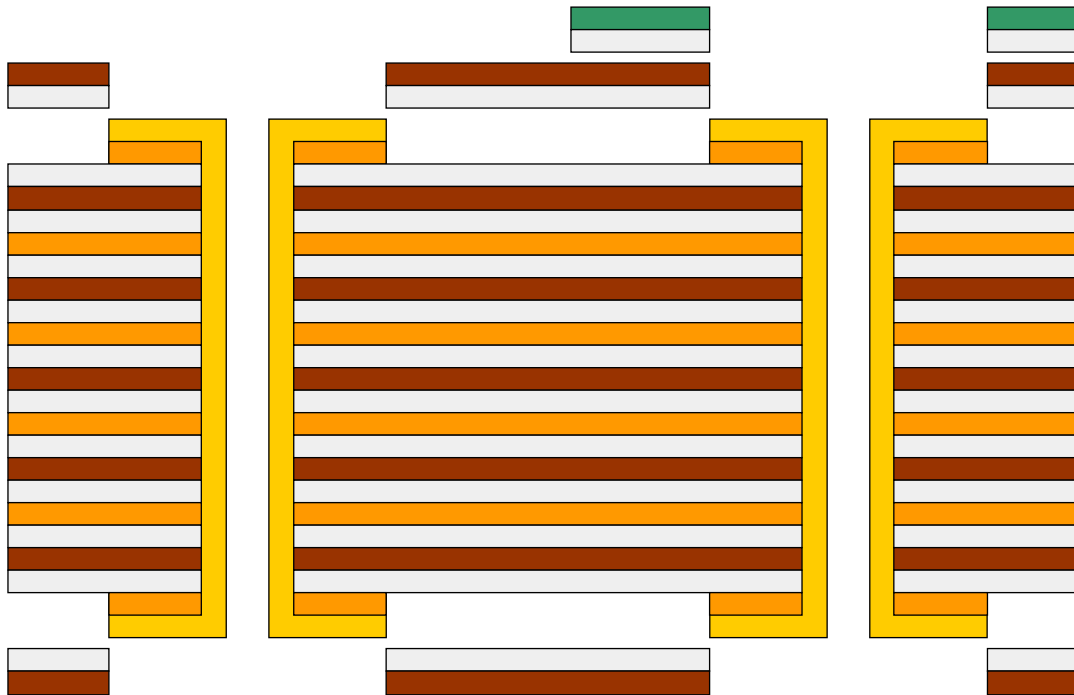







Typical Material Stack up for Type 3 Multi-Layer Flex Circuits



Material Legend

	Copper; Separately per IPC-4562/7 or as Clad Base Stock per IPC-4204/1 or IPC-4204/11
	Adhesive; Separately per IPC 4203/18 or coated onto one or two sides of Kapton per IPC-4203/1
	Kapton; Coated with Adhesive per IPC-4203/1 or Adhesiveless Base Stock Core per IPC-4204/11
	Rigid Stiffener/ Cap Layer; Typically per IPC-4101/21, 24, 40, or 42
	Copper Plating; IPC-6013 / MIL-P-50884

Note: Adhesive or Adhesiveless Base Stocks may be used. Individual material layer thicknesses may be adjusted as required.